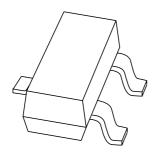
DISCRETE SEMICONDUCTORS

DATA SHEET



BC807 series45 V, 500 mA general purpose transistor

Product specification Supersedes data of 1999 Apr 08 2004 Jan 16





Philips Semiconductors

45 V, 500 mA general purpose transistor

BC807 series

FEATURES

- High current (max. 500 mA)
- Low voltage (max. 45 V).

APPLICATIONS

• General purpose switching and amplification.

DESCRIPTION

PNP transistor in a SOT23 plastic package. NPN complements: BC817.

MARKING

TYPE NUMBER	MARKING CODE(1)
BC807	5D*
BC807-16	5A*
BC807-25	5B*
BC807-40	5C*

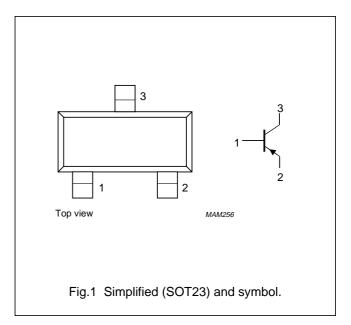
Note

* = p : Made in Hong Kong.
 * = t : Made in Malaysia.

* = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPE	PACKAGE				
NUMBER	NAME	DESCRIPTION	VERSION		
BC807	_	plastic surface mounted package; 3 leads	SOT23		
BC807-16					
BC807-25					
BC807-40					

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-50	V
V _{CEO}	collector-emitter voltage	open base; I _C = -10 mA	_	-45	V
V _{EBO}	emitter-base voltage	open collector	_	- 5	V
I _C	collector current (DC)		_	-500	mA
I _{CM}	peak collector current		_	-1	Α
I _{BM}	peak base current		_	-200	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

^{1.} Transistor mounted on an FR4 printed-circuit board.

45 V, 500 mA general purpose transistor

BC807 series

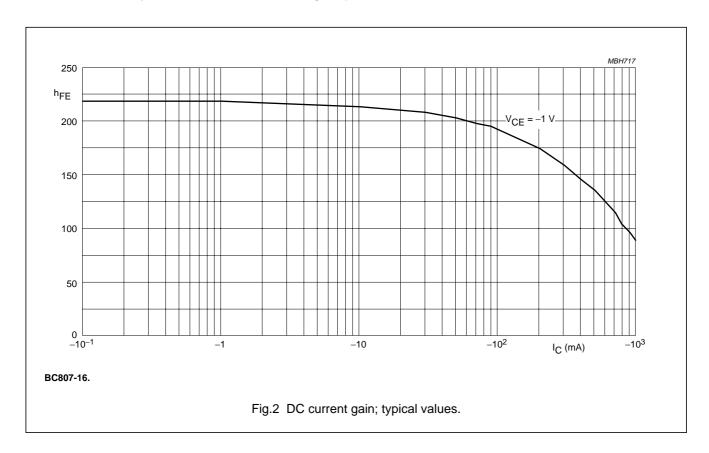
CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = -20 V	_	_	-100	nA
		$I_E = 0$; $V_{CB} = -20 \text{ V}$; $T_j = 150 ^{\circ}\text{C}$	_	_	-5	μΑ
I _{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = -5 \text{ V}$	_	_	-100	nA
h _{FE}	DC current gain	$I_C = -100 \text{ mA}; V_{CE} = -1 \text{ V}; \text{ note 1}$				
	BC807	see Figs 2, 3 and 4	100	-	600	
	BC807-16		100	-	250	
	BC807-25		160	_	400	
	BC807-40		250	_	600	
h _{FE}	DC current gain	$I_C = -500 \text{ mA}; V_{CE} = -1 \text{ V}; \text{ note 1}$	40	_	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -500 \text{ mA}$; $I_B = -50 \text{ mA}$; note 1	_	_	-700	mV
V _{BE}	base-emitter voltage	$I_C = -500 \text{ mA}$; $V_{CE} = -1 \text{ V}$; notes 1 and 2	_	_	-1.2	٧
C _c	collector capacitance	$I_E = I_e = 0$; $V_{CB} = -10 \text{ V}$; $f = 1 \text{ MHz}$	_	9	_	pF
f _T	transition frequency	$I_C = -10 \text{ mA}; V_{CE} = -5 \text{ V}; f = 100 \text{ MHz}$	80	_	_	MHz

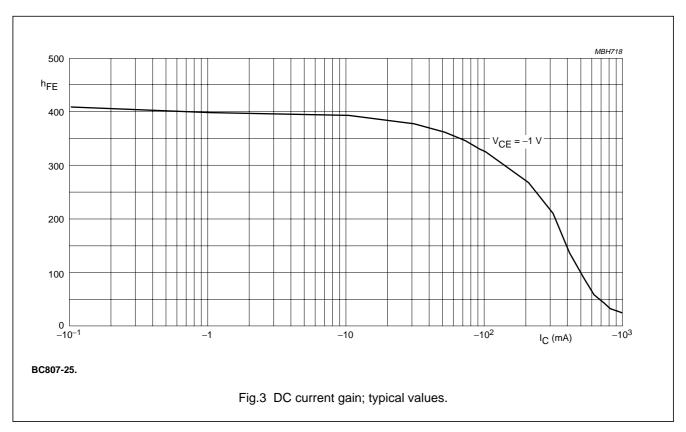
Notes

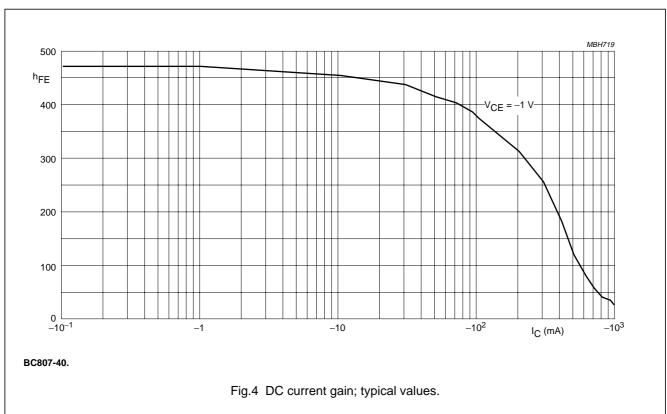
- 1. Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$
- 2. V_{BE} decreases by about -2 mV/K with increasing temperature.



45 V, 500 mA general purpose transistor

BC807 series





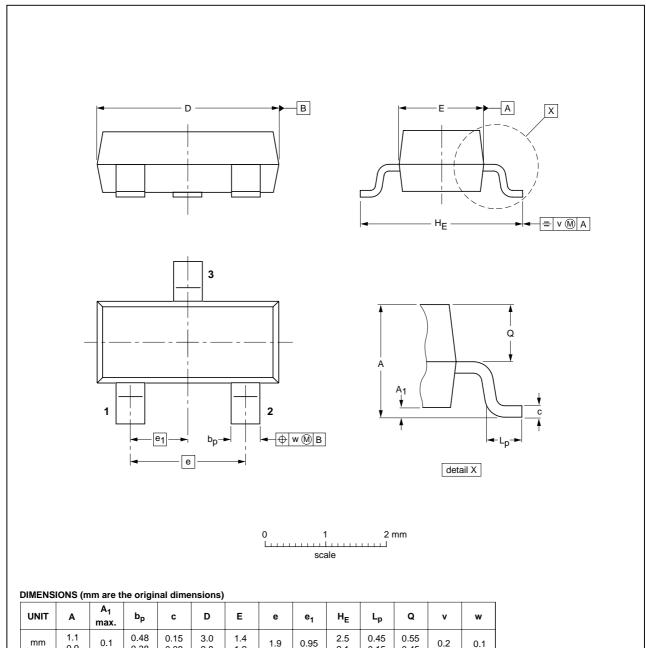
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PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



REFERENCES			EUROPEAN	ISSUE DATE	
IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
	TO-236AB				-97-02-28 99-09-13
	IEC	IEC JEDEC	IEC JEDEC EIAJ	IEC JEDEC EIAJ	IEC JEDEC EIAJ PROJECTION

45 V, 500 mA general purpose transistor

BC807 series

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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